



PMDPB55XPA

20 V, dual P-channel Trench MOSFET

18 March 2024

Product data sheet

1. General description

Dual P-channel enhancement mode Field-Effect Transistor (FET) in a small and leadless ultra thin DFN2020-6 (SOT1118) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Low threshold voltage
- Very fast switching
- Trench MOSFET technology
- Small and leadless ultra thin SMD plastic package: 2 x 2 x 0.65 mm
- Exposed drain pad for excellent thermal conduction
- AEC-Q101 qualified

3. Applications

- DC to DC conversion
- High-speed line driver
- High-side load switch
- Switching circuits

4. Quick reference data

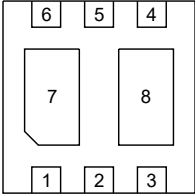
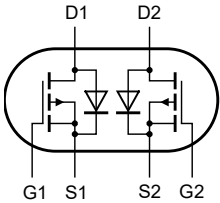
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per transistor							
V_{DS}	drain-source voltage	$T_j = 25\text{ °C}$		-	-	-20	V
V_{GS}	gate-source voltage			-10	-	10	V
I_D	drain current	$V_{GS} = -4.5\text{ V}; T_{amb} = 25\text{ °C}$	[1]	-	-	-3.6	A
Static characteristics (per transistor)							
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = -4.5\text{ V}; I_D = -3.6\text{ A}; T_j = 25\text{ °C}$		-	50	66	mΩ

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S1	source TR1	 Transparent top view DFN2020-6 (SOT1118)	 017aaa258
2	G1	gate TR1		
3	D2	drain TR2		
4	S2	source TR2		
5	G2	gate TR2		
6	D1	drain TR1		
7	D1	drain TR1		
8	D2	drain TR2		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMDPB55XPA	DFN2020-6	plastic, leadless thermal enhanced ultra thin small outline package; no leads; 6 terminals; 0.65 mm pitch; 2 mm x 2 mm x 0.65 mm body	SOT1118

7. Marking

Table 4. Marking codes

Type number	Marking code
PMDPB55XPA	8N

8. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
Per transistor						
V _{DS}	drain-source voltage	T _j = 25 °C		-	-20	V
V _{GS}	gate-source voltage			-10	10	V
I _D	drain current	V _{GS} = -4.5 V; T _{amb} = 25 °C	[1]	-	-3.6	A
		V _{GS} = -4.5 V; T _{amb} = 100 °C	[1]	-	-2.3	A
		V _{GS} = -4.5 V; T _{sp} = 25 °C		-	-9.3	A
I _{DM}	peak drain current	T _{amb} = 25 °C; single pulse; t _p ≤ 10 μs		-	-37	A
P _{tot}	total power dissipation	T _{amb} = 25 °C	[2]	-	490	mW
			[1]	-	1.2	W
		T _{sp} = 25 °C		-	8.3	W
Per device						
P _{tot}	total power dissipation	T _{amb} = 25 °C	[2]	-	640	mW
			[1]	-	1.6	W
		T _{sp} = 25 °C		-	11	W
T _j	junction temperature			-55	150	°C
T _{amb}	ambient temperature			-55	150	°C
T _{stg}	storage temperature			-65	150	°C
Source-drain diode (per transistor)						
I _S	source current	T _{amb} = 25 °C	[1]	-	-1.2	A
Avalanche ruggedness (per transistor)						
E _{DS(AL)S}	non-repetitive drain-source avalanche energy	T _{J(init)} = 25 °C; I _D = -0.65 A; DUT in avalanche (unclamped)		-	4.4	mJ

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².
[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

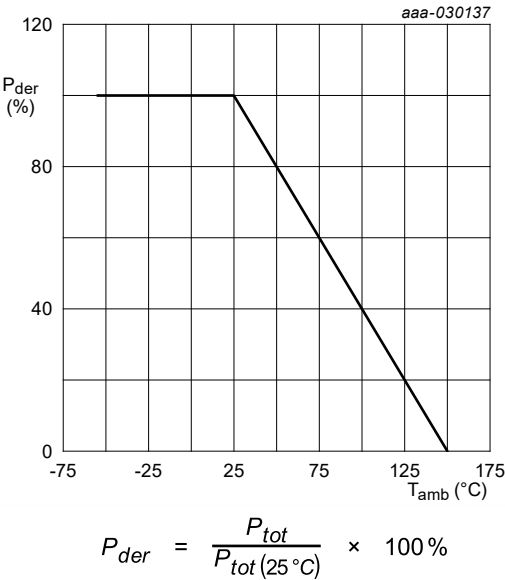


Fig. 1. Normalized total power dissipation as a function of ambient temperature

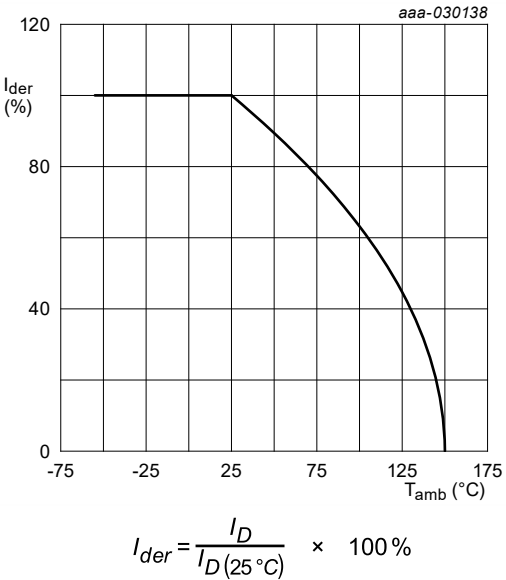


Fig. 2. Normalized continuous drain current as a function of ambient temperature

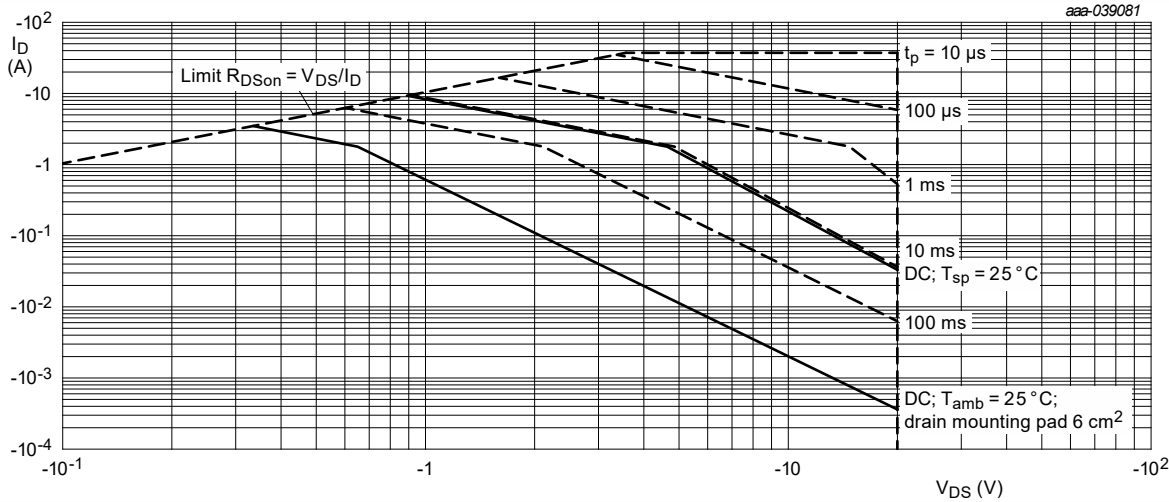


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per transistor							
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	223	256	K/W
			[2]	-	93	107	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	10	15	K/W
Per device							
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	190	K/W
			[2]	-	-	80	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	-	11	K/W

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm².

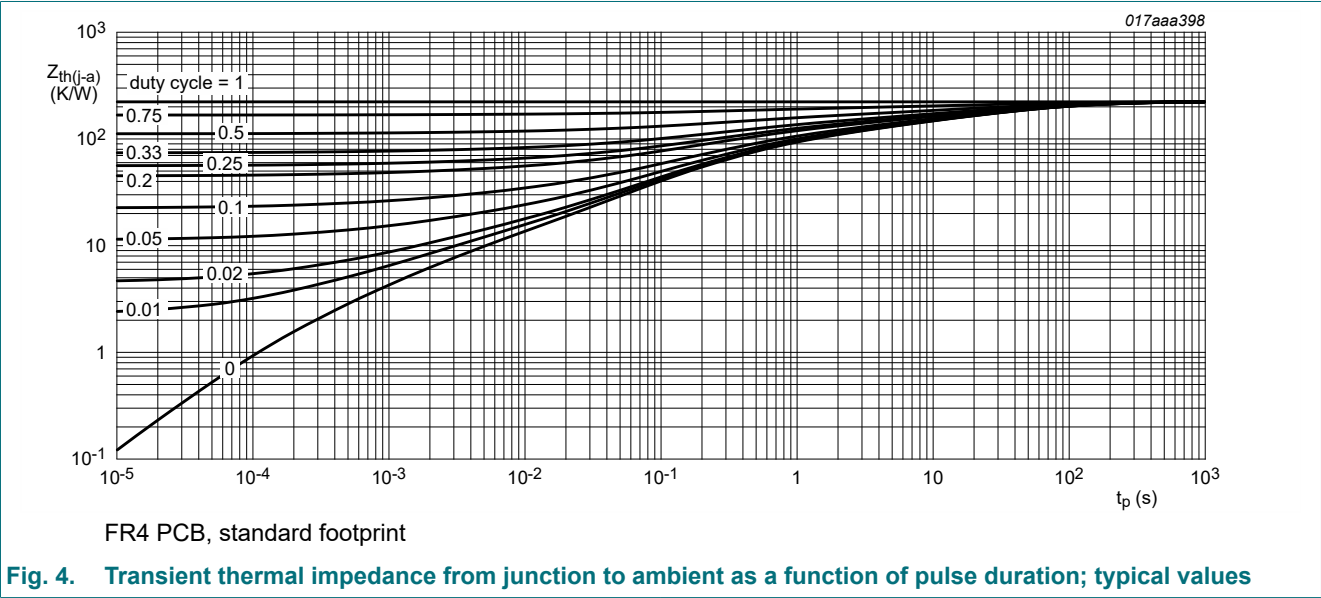
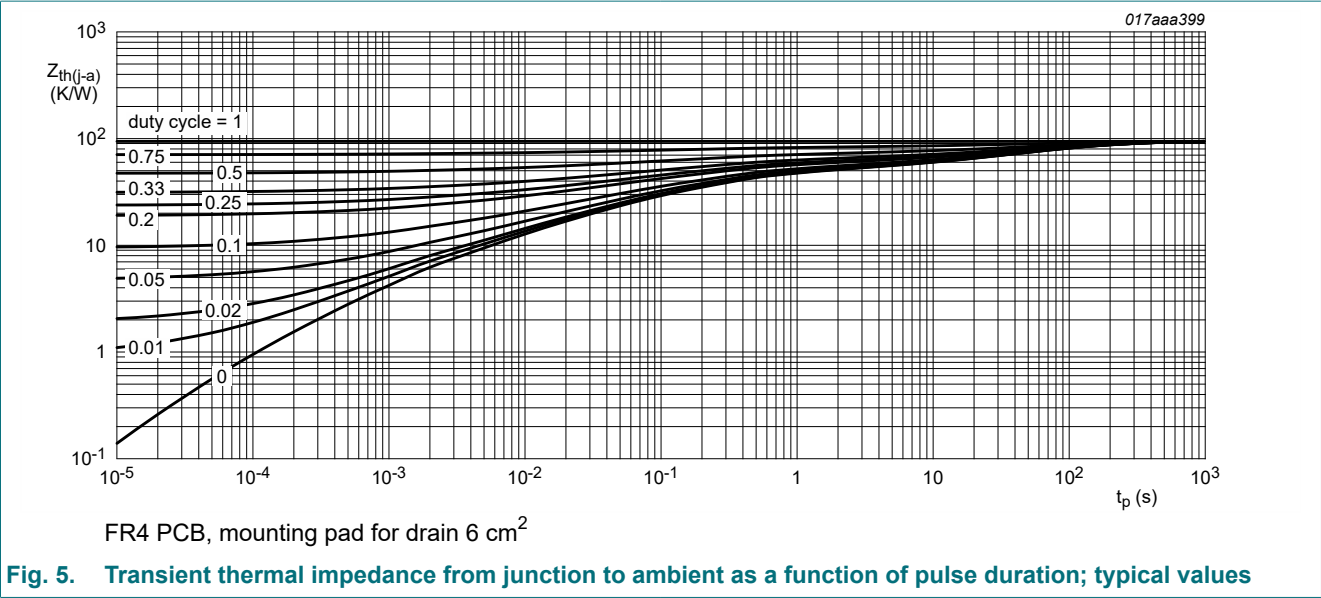


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics (per transistor)							
V _{(BR)DSS}	drain-source breakdown voltage	I _D = -250 μA; V _{GS} = 0 V; T _j = 25 °C		-20	-	-	V
V _{GSth}	gate-source threshold voltage	I _D = -250 μA; V _{DS} = V _{GS} ; T _j = 25 °C		-0.47	-0.65	-1	V
I _{DSS}	drain leakage current	V _{DS} = -20 V; V _{GS} = 0 V; T _j = 25 °C		-	-	-1	μA
I _{GSS}	gate leakage current	V _{GS} = -10 V; V _{DS} = 0 V; T _j = 25 °C		-	-	-100	nA
		V _{GS} = 10 V; V _{DS} = 0 V; T _j = 25 °C		-	-	100	nA
R _{DSon}	drain-source on-state resistance	V _{GS} = -4.5 V; I _D = -3.6 A; T _j = 25 °C		-	50	66	mΩ
		V _{GS} = -4.5 V; I _D = -3.6 A; T _j = 150 °C		-	73	96	mΩ
		V _{GS} = -2.5 V; I _D = -2.6 A; T _j = 25 °C		-	62	87	mΩ
		V _{GS} = -1.8 V; I _D = -0.5 A; T _j = 25 °C		-	83	135	mΩ
g _{fs}	forward transconductance	V _{DS} = -10 V; I _D = -3.6 A; T _j = 25 °C		-	12	-	S
Dynamic characteristics (per transistor)							
Q _{G(tot)}	total gate charge	V _{DS} = -10 V; I _D = -3.6 A; V _{GS} = -4.5 V; T _j = 25 °C		-	8.8	13	nC
Q _{GS}	gate-source charge			-	1.2	-	nC
Q _{GD}	gate-drain charge			-	2.4	-	nC
C _{iss}	input capacitance	V _{DS} = -10 V; f = 1 MHz; V _{GS} = 0 V; T _j = 25 °C		-	785	-	pF
C _{oss}	output capacitance			-	70	-	pF
C _{rss}	reverse transfer capacitance			-	62	-	pF
t _{d(on)}	turn-on delay time	V _{DS} = -10 V; I _D = -3.6 A; V _{GS} = -4.5 V; R _{G(ext)} = 6 Ω; T _j = 25 °C		-	11	-	ns
t _r	rise time			-	2	-	ns
t _{d(off)}	turn-off delay time			-	55	-	ns
t _f	fall time			-	135	-	ns
Source-drain diode (per transistor)							
V _{SD}	source-drain voltage	I _S = -1.2 A; V _{GS} = 0 V; T _j = 25 °C		-	-0.8	-1.2	V
t _{rr}	reverse recovery time	I _S = -2 A; dI _S /dt = 60 A/μs; V _{GS} = -4.5 V; V _{DS} = -20 V; T _j = 25 °C		-	14	-	ns
Q _r	recovered charge			-	4.8	-	nC

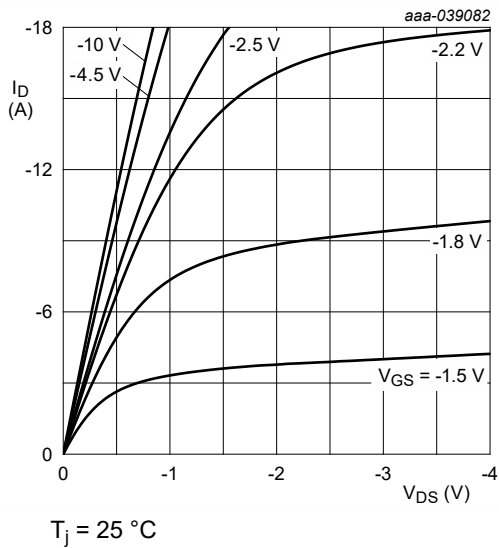


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

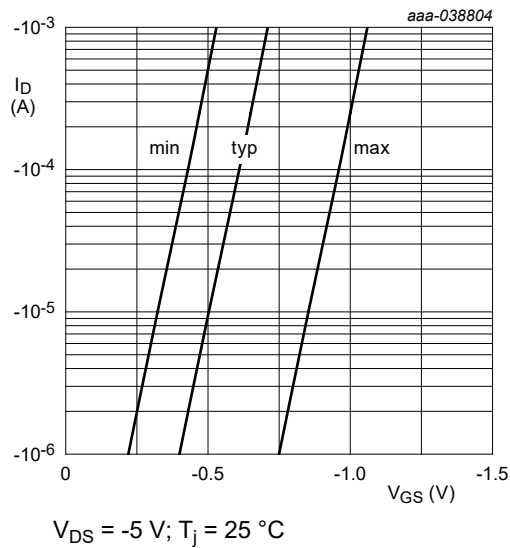


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

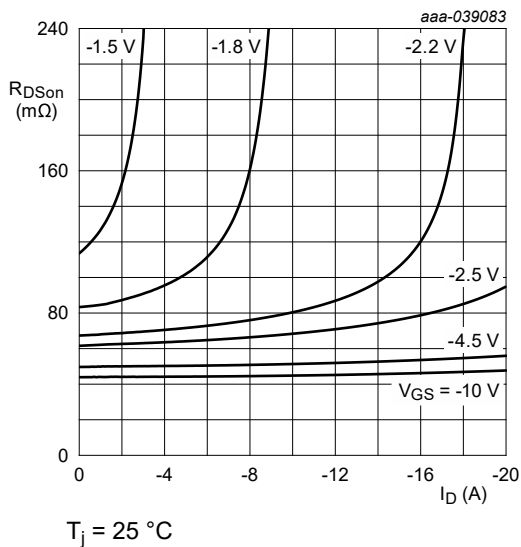


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

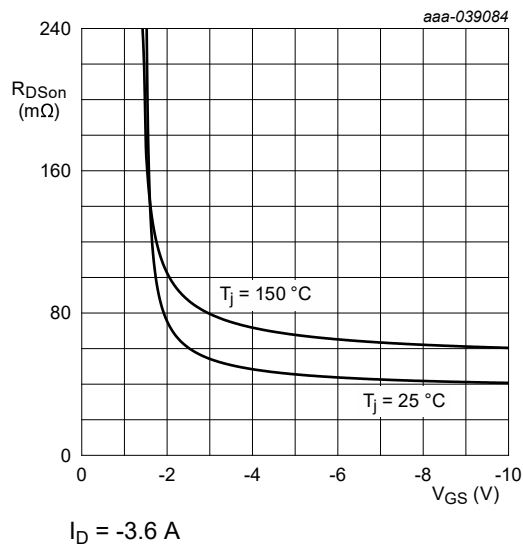


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

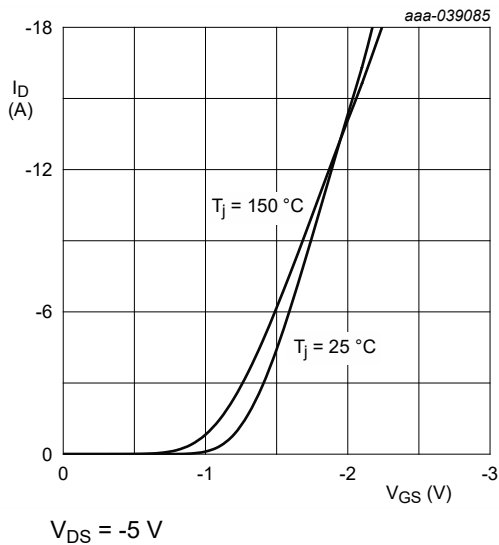


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

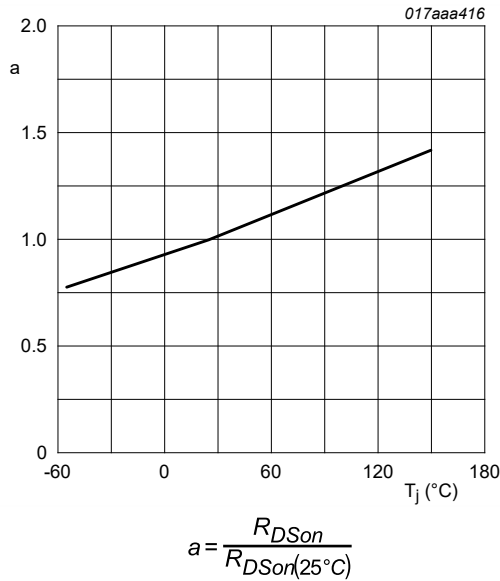


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

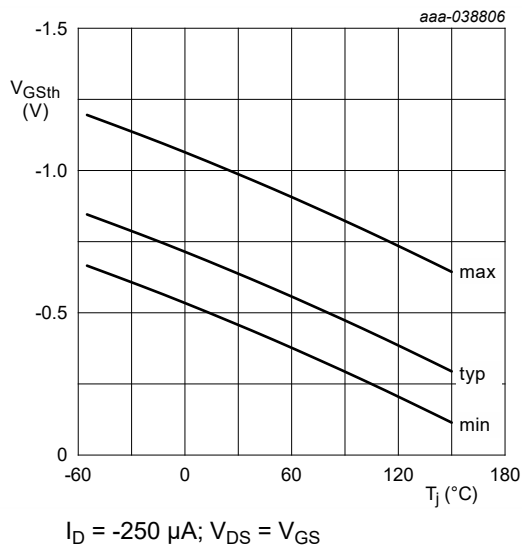


Fig. 12. Gate-source threshold voltage as a function of junction temperature

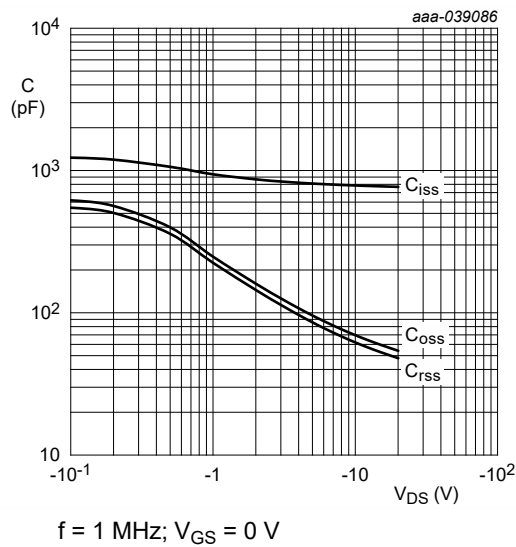


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

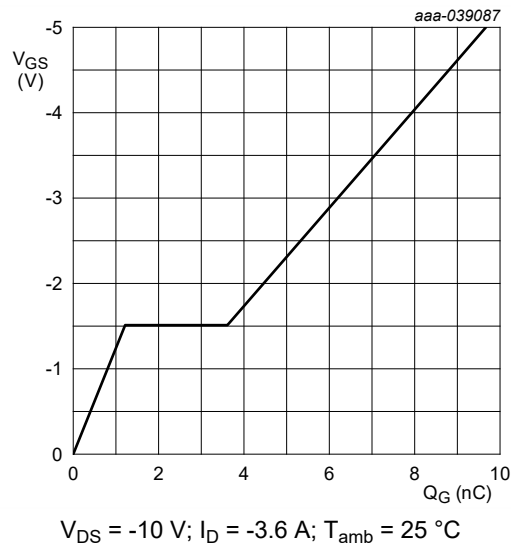


Fig. 14. Gate-source voltage as a function of gate charge; typical values

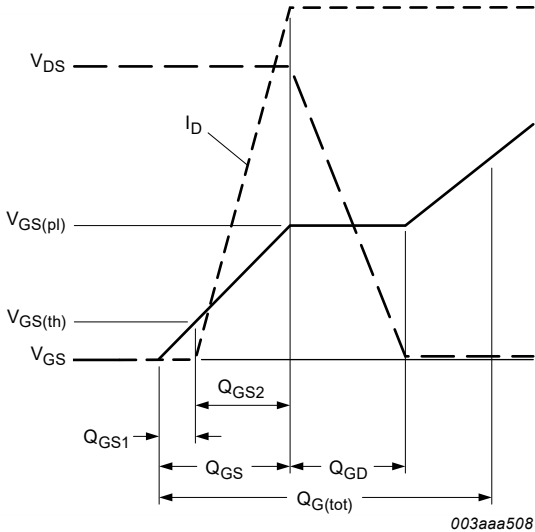


Fig. 15. Gate charge waveform definitions

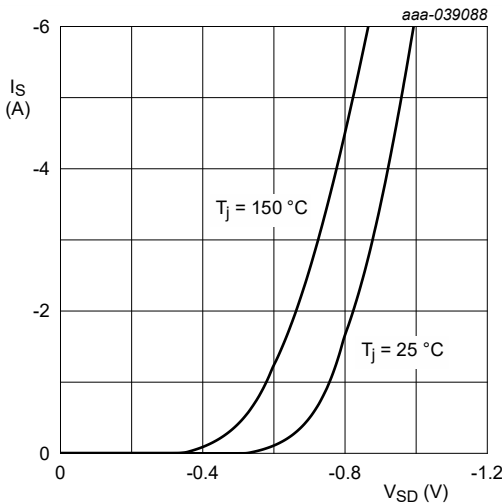


Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information

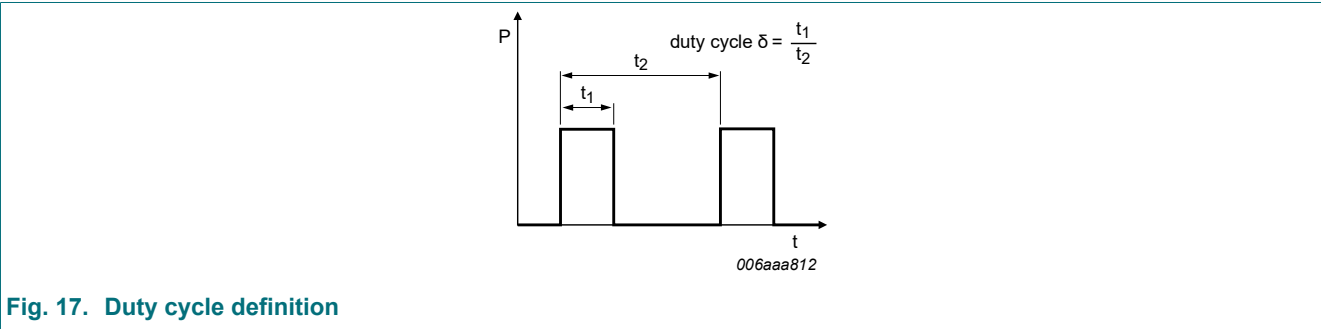


Fig. 17. Duty cycle definition

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

HUSON6: plastic, thermal enhanced ultra thin small outline package; no leads;
6 terminals; body 2 x 2 x 0.65 mm

SOT1118

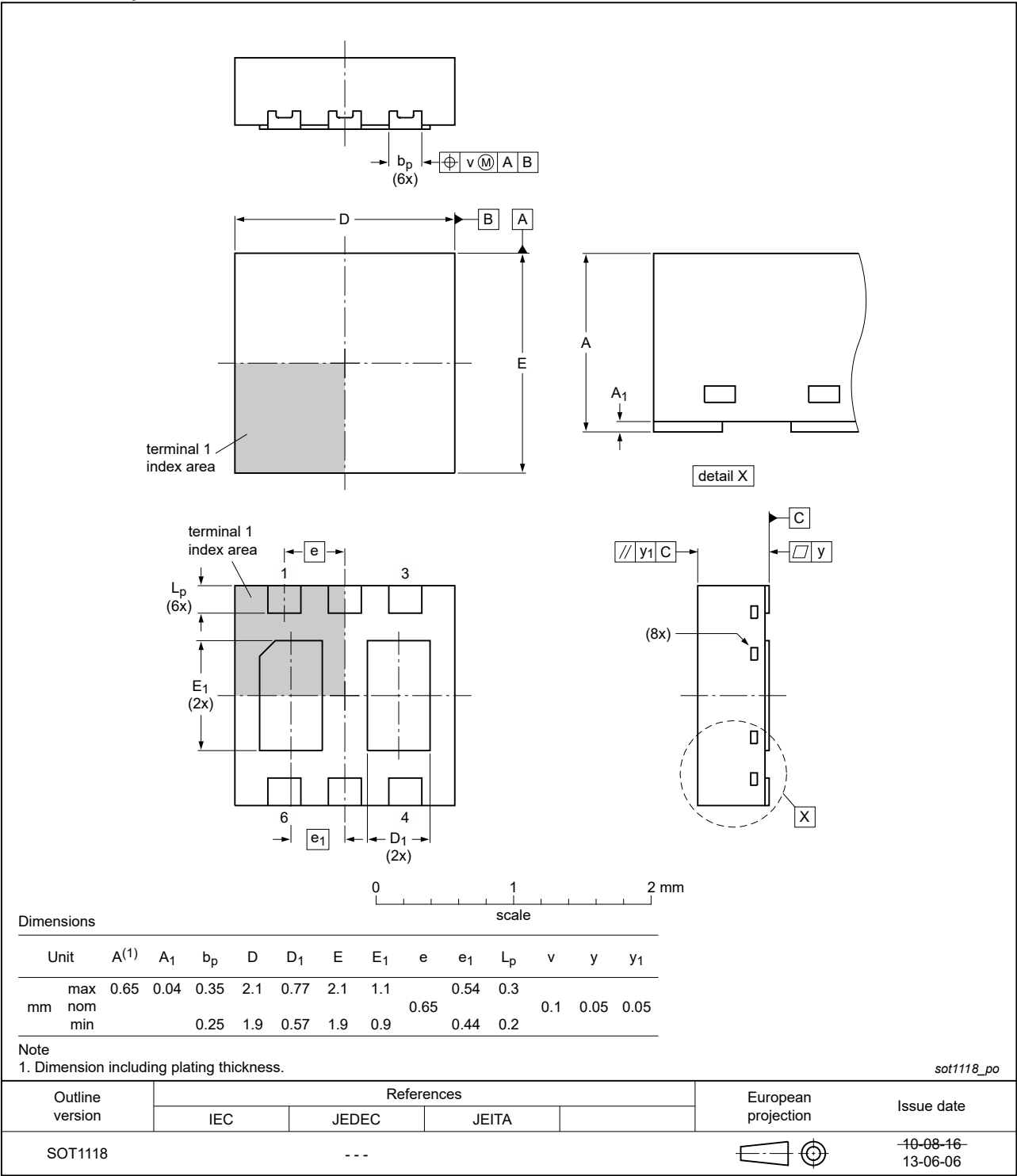


Fig. 18. Package outline DFN2020-6 (SOT1118)

13. Soldering

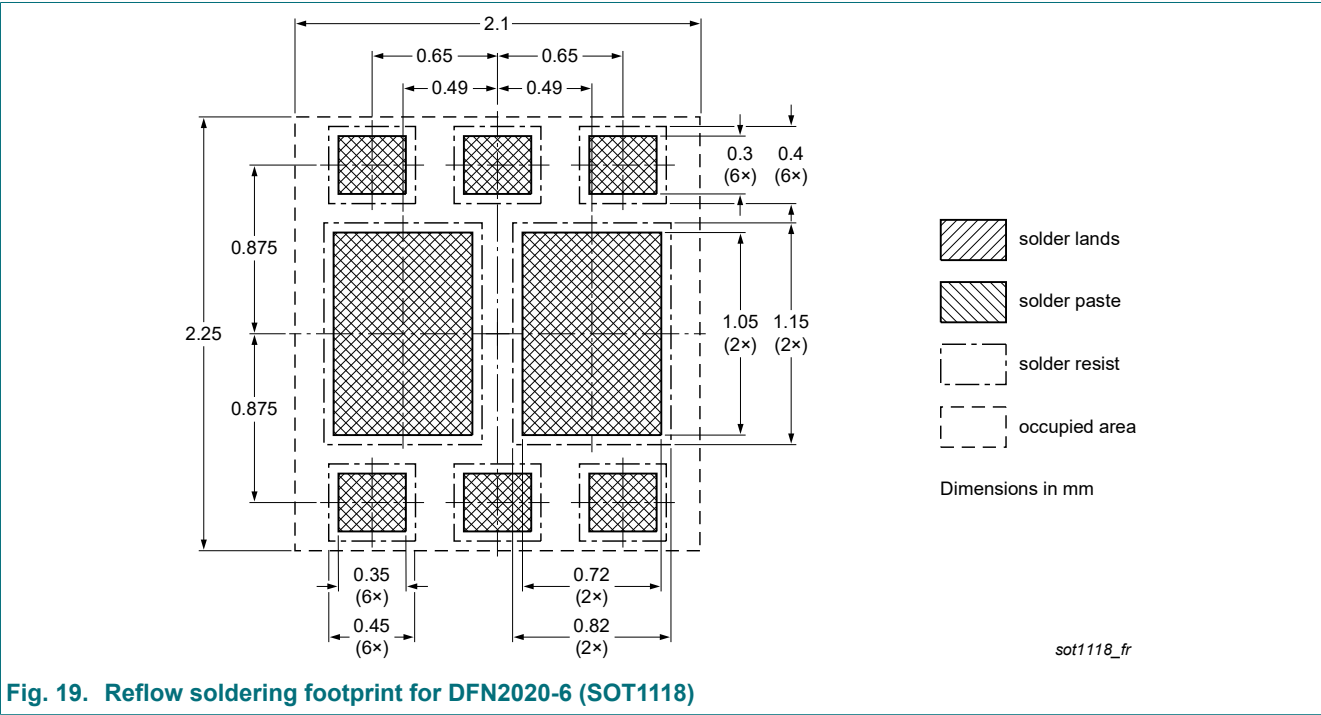


Fig. 19. Reflow soldering footprint for DFN2020-6 (SOT1118)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMDPB55XPA v.1	20240318	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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